

# Thoughts on fast gate drive

M.D. Young

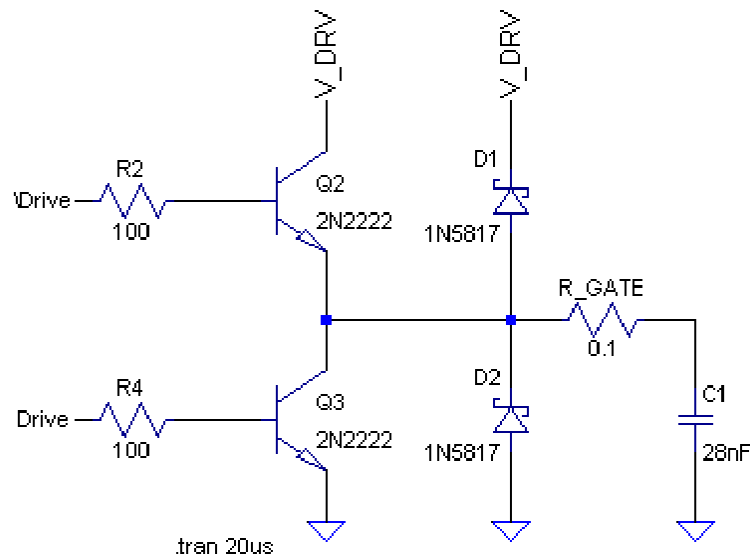
16-Apr-2010

# Purpose

- Propose circuit architecture capable to driving a  $\sim 28\text{nF}$  MOSFET gate at 500kHz
- Perform ROM calculations of losses

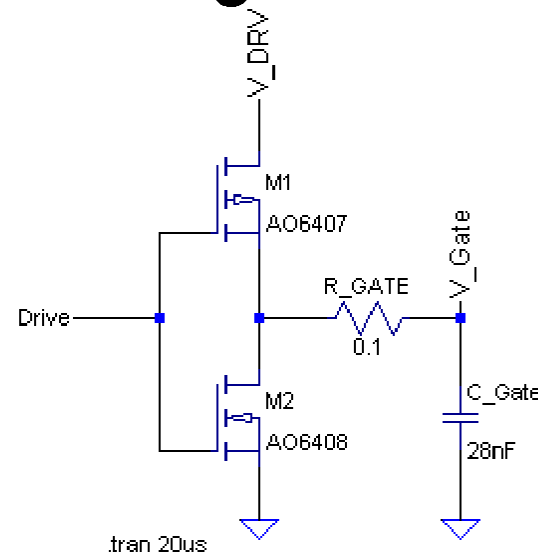
# Option 1: Bipolar transistor drive

- Schottkys are needed to provide current path for inevitable ring between gate capacitance and parasitic inductance
- Turnoff speed uninspiring; requires bipolar drive



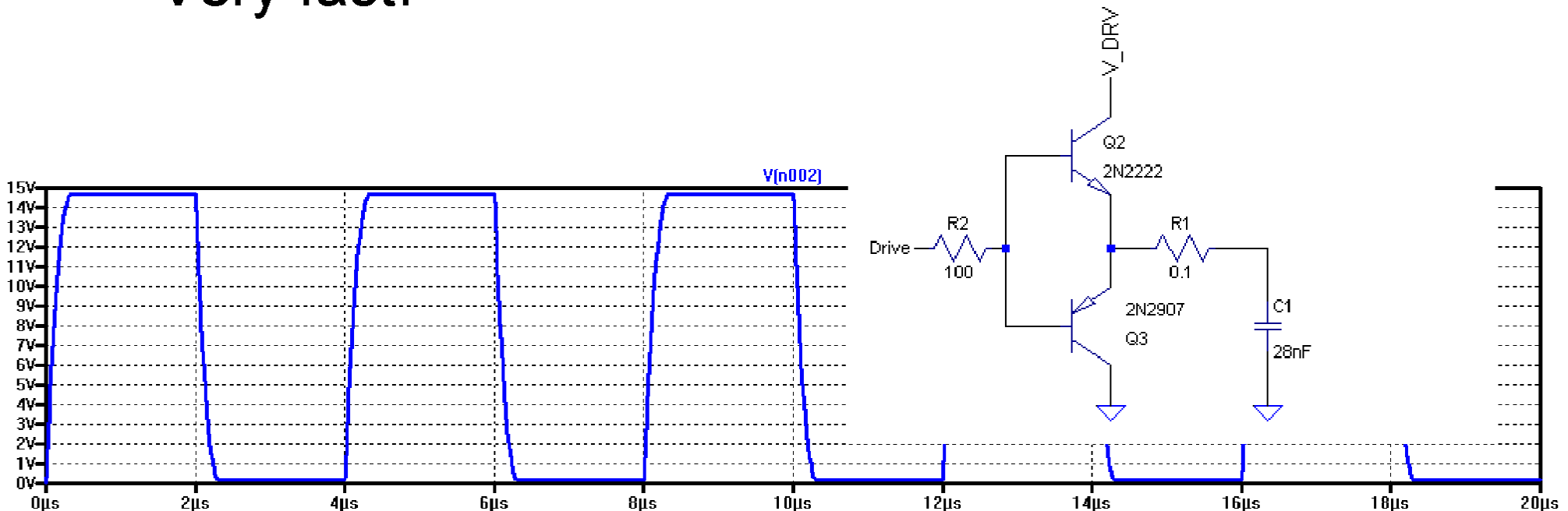
# Option 2: MOSFET Totem Pole

- Very fast switching circuit
- Fundamentally flawed: shoot-through current during period when both FETs are in conduction
- Can be mitigated through timing circuitry, but this adds complexity to design



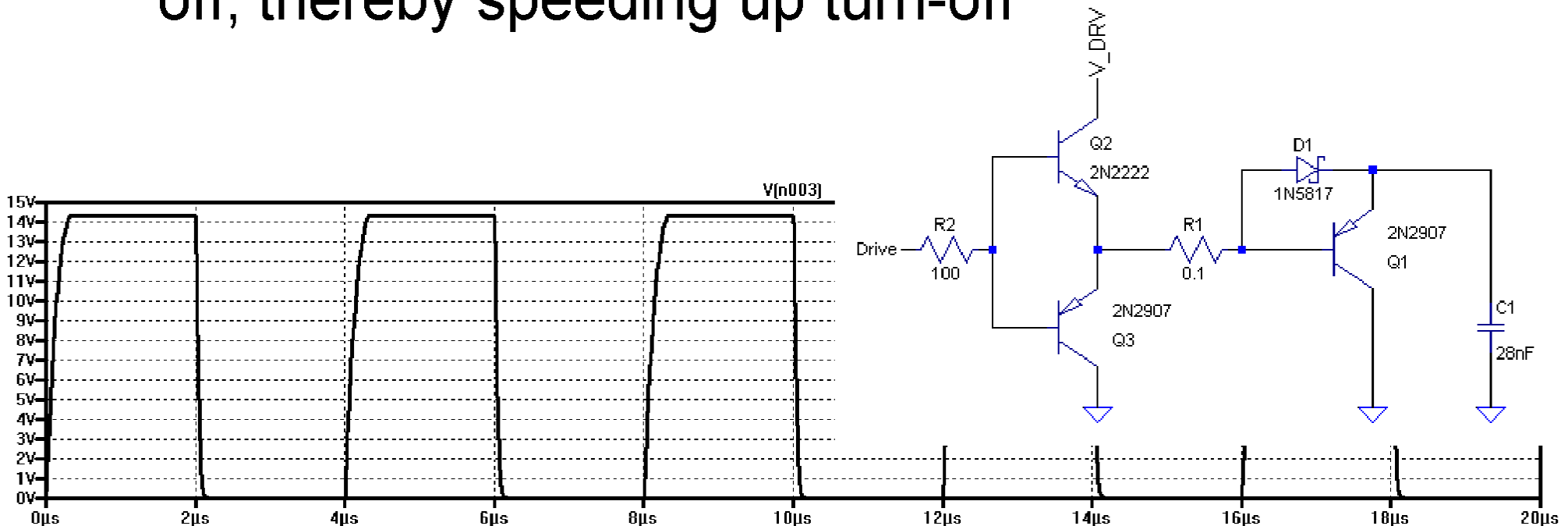
# Option 3: Bipolar totem pole

- Avoids shoot-through problem of FET totem pole
- The two B-E junctions protect each other from reverse breakdown; does not require any Schottky diodes for reverse current protection
- Very fast!

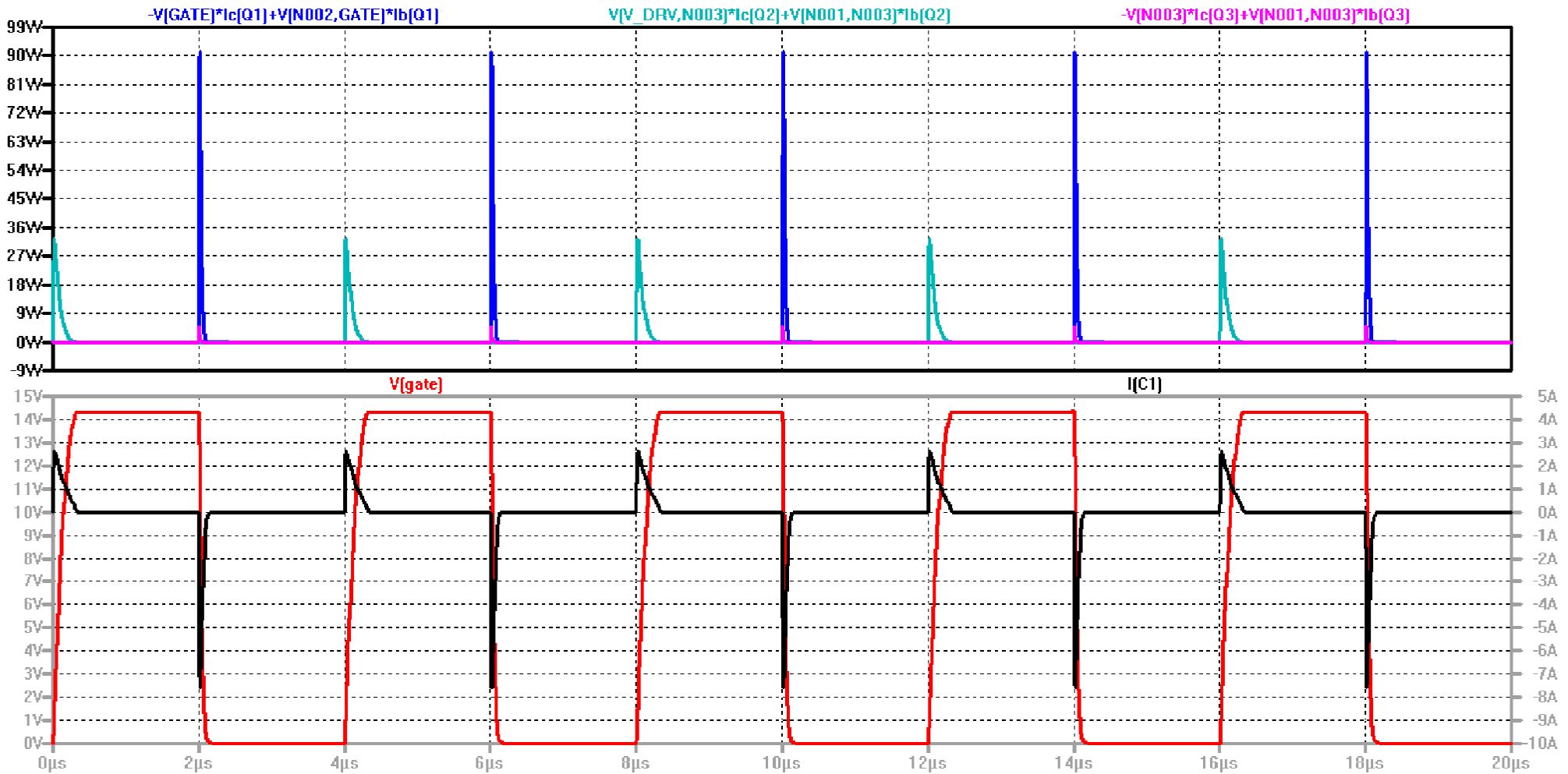


# Option 3A: Bipolar totem w/ speedup

- Add a turn-off speed-up subcircuit
- Schottky provides current path to charge gate, and protects Q1 from B-E breakdown
- Q1 provides shunt for gate capacitance at turn-off; thereby speeding up turn-off



# Option 3A (totem + speedup)



# Option 3A (totem + speedup)

- Observations:
  - Maximum stress is on Q1 (turn-off transistor)
    - Peak power dissipation  $\sim 90\text{W}$ ; average  $\sim 700\text{mW}$
    - Peak current  $\sim 8\text{A}$ ; RMS  $\sim 720\text{mA}$
  - Stress on Q2 (NPN, top of totem pole)
    - Peak power dissipation  $\sim 33\text{W}$ ; average  $\sim 700\text{mW}$
    - Peak current  $\sim 2.5\text{A}$ ; RMS  $\sim 400\text{mA}$
  - Stress on Q3 (PNP, bottom of totem pole)
    - Peak power dissipation  $\sim 5\text{W}$ ; average  $\sim 15\text{mW}$
    - Peak current  $650\text{mA}$ ; RMS  $\sim 58\text{mA}$



# Option 3A (totem + speedup)

- Observations:
  - Rise time:  $\sim 320\text{ns}$
  - Fall time:  $\sim 40\text{ns}$
- Peak drive current  $\sim 3\text{A}$

# Power FET + Parasitics

- Microsemi APTM20DAM04G module
- Switching 100V @ 200A, purely resistive
- Assumed junction temperature of 125DegC
- 50% duty cycle, 500kHz switching frequency

<b>Data sheet values</b>			
C <sub>ISS</sub>	28900	pF	Input capacitance
C <sub>OSS</sub>	9320	pF	Output capacitance
C <sub>RSS</sub>	580	pF	Reverse transfer capacitance
g <sub>f</sub>	86	I/A	Forward transconductance
V <sub>DS spec</sub>	25	V	Voltage at which C <sub>RSS</sub> is specified
R <sub>G,I</sub>	2.1	Ohm	Internal gate mesh resistance
V <sub>T</sub>	5	V	Spec sheet threshold
Q <sub>G</sub>	5.60E-07	C	Gate charge

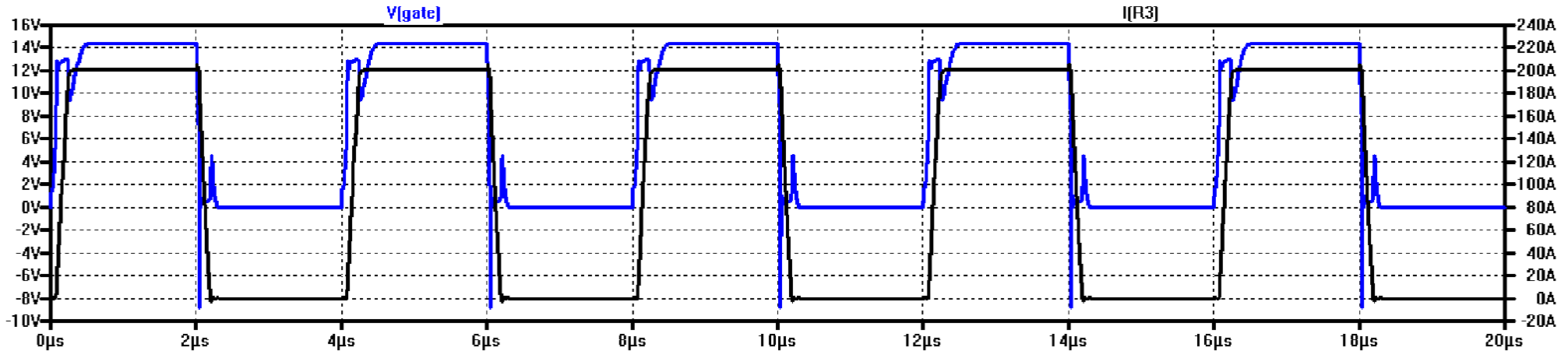
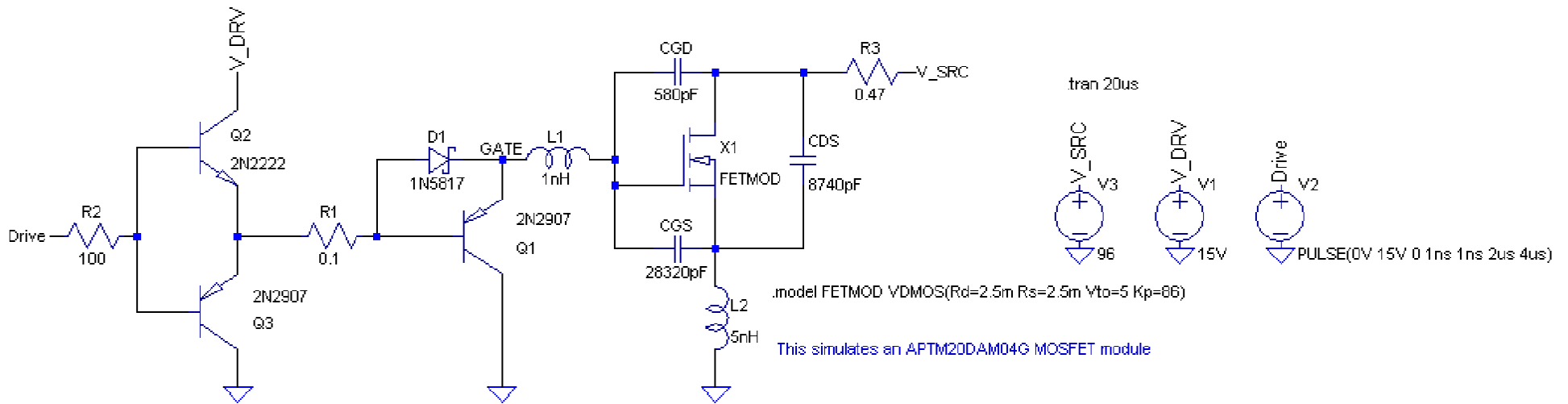
<b>Circuit conditions</b>			
V <sub>DS off</sub>	100	V	Voltage standoff of FET
Temp Rise	100	K	Temperature rise above ambient
Drain current	200	A	Expected drain current, fully saturated
R <sub>Low</sub>	0.1	Ohm	Internal impedance of gate driver, low side
R <sub>High</sub>	0.1	Ohm	Internal impedance of gate driver, high side
R <sub>Gate</sub>	0.1	Ohm	Series resistance between gate driver and gate
F <sub>Drv</sub>	500000	Hz	Switching frequency
V <sub>Drv</sub>	15	V	Gate drive voltage
L <sub>Source</sub>	5	nH	Parasitic source inductance

# Power FET + Parasitics

- Rule-of-thumb worksheet results
  - Negative R\_G optimum means zero added gate resistance is required
  - Parasitic capacitances and temperature-derated thresholds computed
  - WARNING: Switching loss is purely linear region loss, NOT R<sub>ds</sub>..

<b>Model outputs</b>			
C_GD_AVG	580	pF	Average-case gate / drain capacitance
C_OSS_AVG	9320	pF	Average-case OSS parasitic capacitance
C_GD	580	pF	Gate / drain capacitance
C_GS	28320	pF	Gate / source capacitance
C_DS	8740	pF	Drain / source capacitance
VT_Derated	4.3	V	Turn-on threshold, adjusted for temperature
V_GS_Miller	6.625581395	V	Miller plateau level (gate drive at departure from linear)
P_Gate	4.20E+00	W	Gate charge losses
I_Gate_Avg	2.80E-01	A	Average gate drive current
P_Drv_On	9.13E-02	W	Power dissipation in gate driver, turn on
P_Drv_Off	9.13E-02	W	Power dissipation in gate driver, turn off
P_Drv_Total	1.83E-01	W	Power dissipation in gate driver, total
I_G2	4.1466	A	Drive gate current during interval when V <sub>gs</sub> rises from V <sub>t</sub> to Miller Plateau
I_G3	3.6411	A	Drive gate current during Miller Plateau region
t_2	1.62E-08	s	Switching time in region 2
t_3	1.59E-08	s	Switching time in region 3
P_SW	1.61E+02	W	Estimate of switching losses in FET
R_G_Optimum	0.00	Ohm	Optimum value of gate resistance to minimize gate drive ringing

# Power FET + Parasitics



# Power FET + Parasitics

- Average load dissipation: 9kW
- Average MOSFET dissipation: 400W
- Average Q1 dissipation: 580mW
- Average Q2 dissipation: 660mW
- Average Q3 dissipation: 14mW
  
- Turn-on time: 250ns
- Turn-off time: 210ns
  
- Drive current into totem pole: 150mA<sub>p-p</sub> @ 15V

# RECOMMENDATION

- The bipolar totem pole with speedup transistor seems to have a lot of promise
- The specific bipolar transistors used in the totem pole need to be optimized
- NOTE: Given the current levels and power dissipation of the NPN and PNP drive transistors, DPAK or TO-220 packages will be needed. Everything must be as close to the MOSFET gate/source terminals as possible, with an absolute minimum possible inductance. Highly effective decoupling capacitors will be needed for drive.